



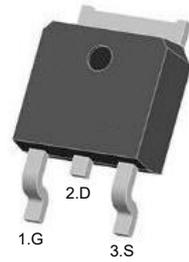
PJM10H50PTE

P-Channel Enhancement Mode Power MOSFET

Features

- Excellent $R_{DS(on)}$
- Advanced trench process technology
- $V_{DS} = -100V, I_D = -50A$
 $R_{DS(on)} < 50m\Omega @ V_{GS} = -10V$

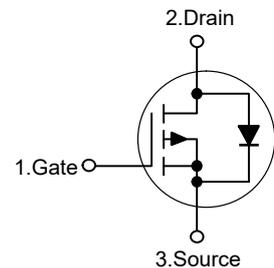
TO-252



Applications

- Power switch
- DC/DC converters

Schematic Diagram



Absolute Maximum Ratings

Ratings at 25°C Case temperature unless otherwise specified.

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$-V_{DS}$	100	V
Gate-Source Voltage	V_{GS}	± 20	V
Drain Current-Continuous and $V_{GS} = 10V$ ^{Note1}	$-I_D$	50	A
Drain Current-Pulsed ^{Note2}	$-I_{DM}$	100	A
Single Pulse Avalanche Energy ^{Note3}	E_{AS}	345	mJ
Avalanche Current	I_{AS}	28	A
Maximum Power Dissipation ^{Note4}	P_D	104	W
Junction Temperature	T_J	150	°C
Storage Temperature Range	T_{STG}	-55 to +150	°C

Thermal Characteristics

Thermal Resistance, Junction-to-Ambient ^{Note1}	$R_{\theta JA}$	62	°C/W
Maximum Junction-to-Case ^{Note1}	$R_{\theta JC}$	1.2	°C/W



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Electrical Characteristics

(T_J=25°C unless otherwise specified)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	-V _{(BR)DSS}	V _{GS} =0V, I _D =-250μA	100	--	--	V
Zero Gate Voltage Drain Current	-I _{DSS}	V _{DS} =-100V, V _{GS} =0V, T _J =25°C	--	--	1	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V, V _{DS} =0V	--	--	±100	nA
Gate Threshold Voltage ^{Note2}	-V _{GS(th)}	V _{DS} =V _{GS} , I _D =-250μA	1.0	1.8	2.5	V
Drain-Source On-Resistance ^{Note2}	R _{DS(on)}	V _{GS} =-10V, I _D =-10A	--	42	50	mΩ
		V _{GS} =-4.5V, I _D =-8A	--	46	55	mΩ
Forward Transconductance ^{Note2}	g _{FS}	V _{DS} =-10V, I _D =-10A	--	32	--	S
Dynamic Characteristics						
Input Capacitance	C _{iss}	V _{DS} =-25V, V _{GS} =0V, f = 1MHz	--	6516	--	pF
Output Capacitance	C _{oss}		--	223	--	pF
Reverse Transfer Capacitance	C _{rss}		--	125	--	pF
Switching Characteristics						
Turn-on Delay Time	t _{d(on)}	V _{DD} =-50V, I _D =-14A, V _{GS} =-10V, R _G =3.3Ω	--	20.5	--	nS
Turn-on Rise Time	t _r		--	32.2	--	nS
Turn-off Delay Time	t _{d(off)}		--	123	--	nS
Turn-off Fall Time	t _f		--	63.7	--	nS
Total Gate Charge	Q _g	V _{DS} =-80V, I _D =-14A, V _{GS} =-10V	--	92	--	nC
Gate-Source Charge	Q _{gs}		--	17.5	--	nC
Gate-Drain Charge	Q _{gd}		--	14	--	nC
Source-Drain Diode Characteristics						
Diode Forward Voltage ^{Note2}	-V _{SD}	V _{GS} =0V, I _S =-1A, T _J =25°C	--	--	1.2	V
Diode Forward Current ^{Note1,5}	-I _S		--	--	35	A

Note :

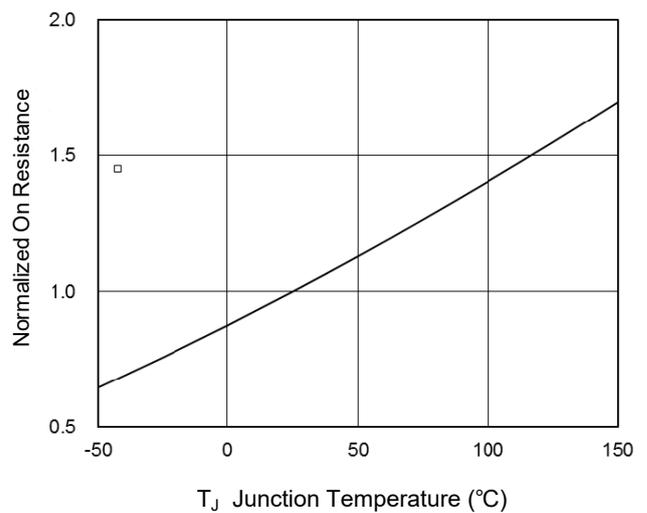
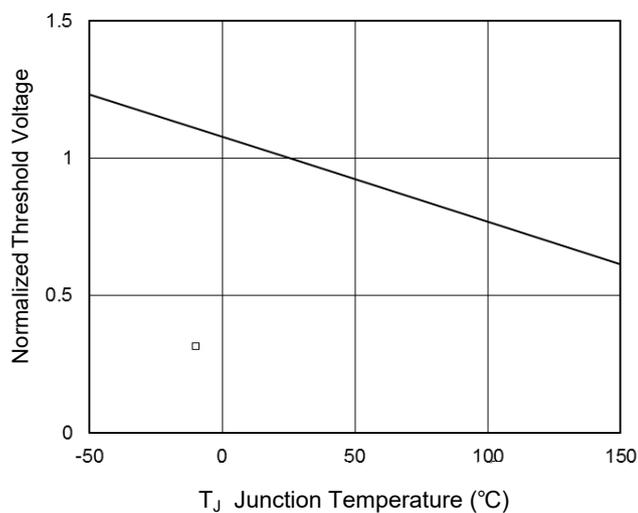
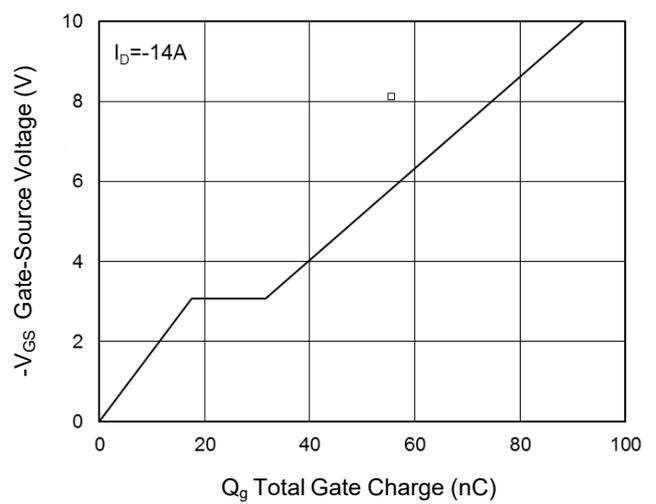
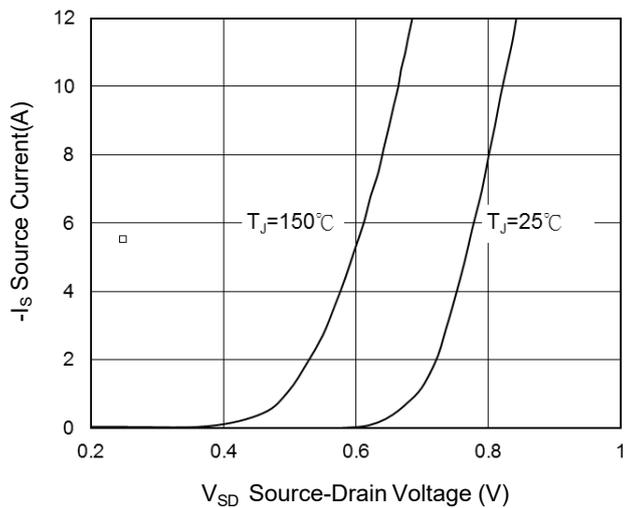
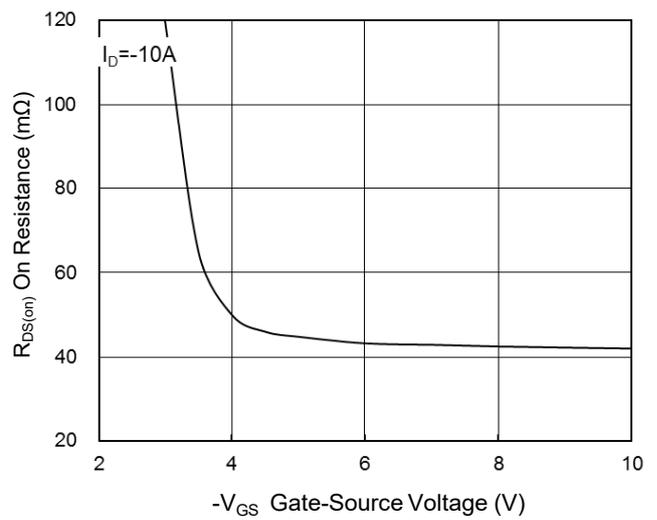
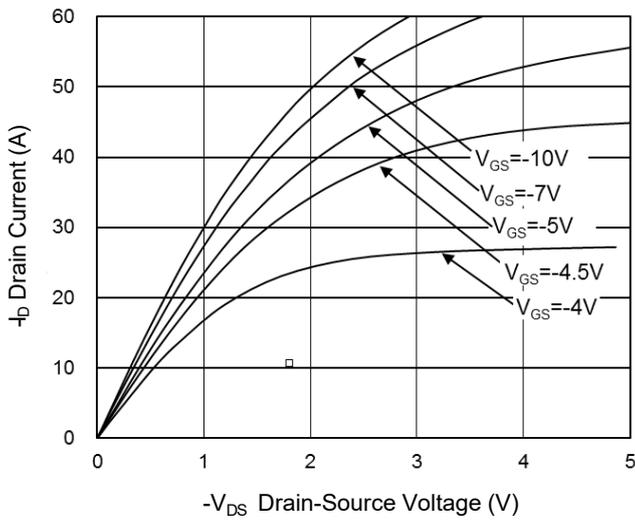
- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%
- 3.The E_{AS} data shows Max. rating . The test condition is V_{DD}=-25V, V_{GS}=-10V, L=0.88mH, I_{AS}=-28A
- 4.The power dissipation is limited by 150°C junction temperature
- 5.The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.



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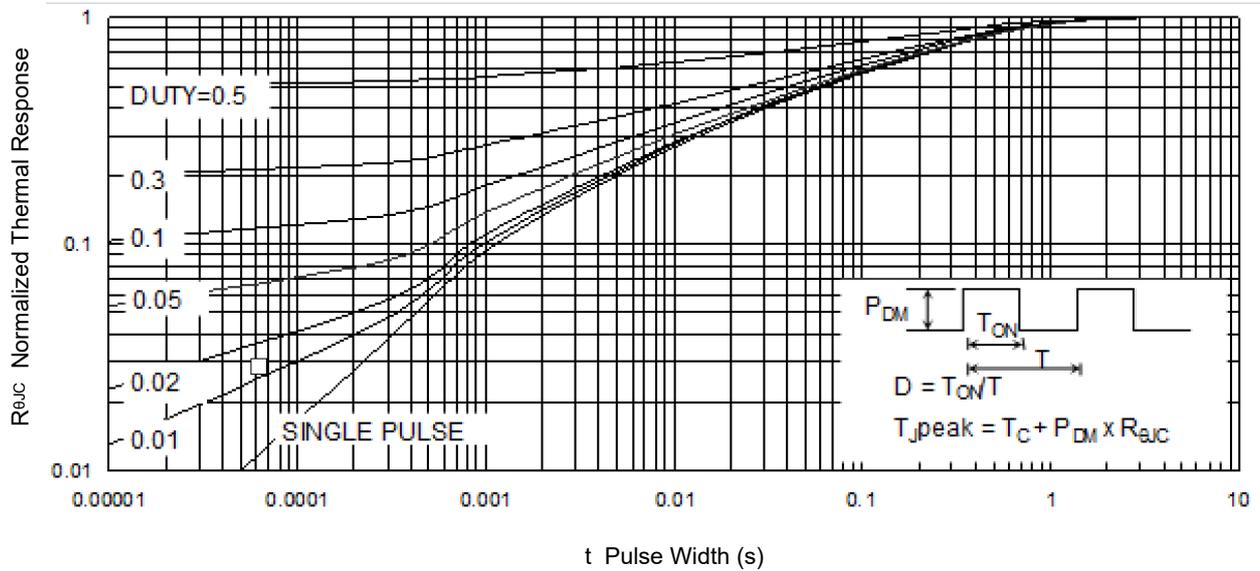
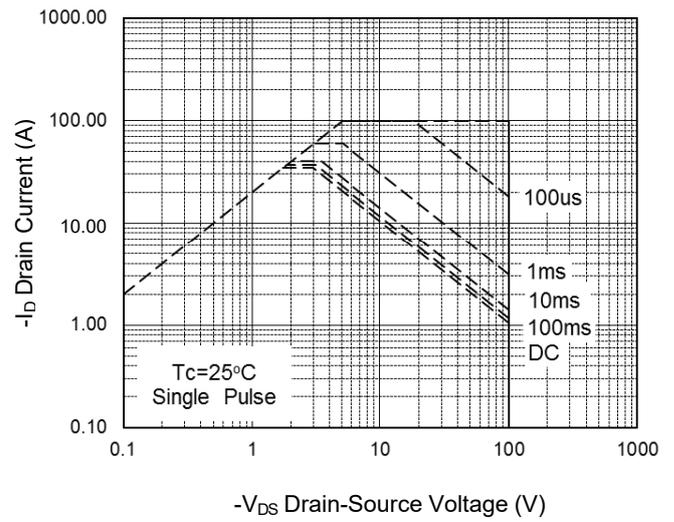
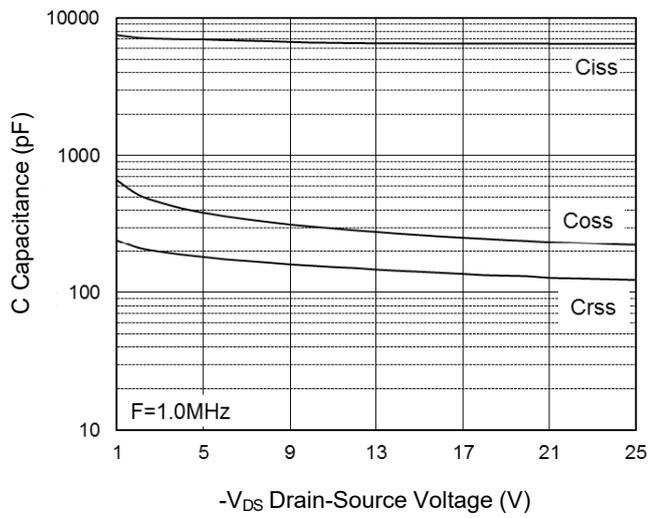
Typical Characteristic Curves

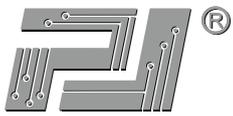




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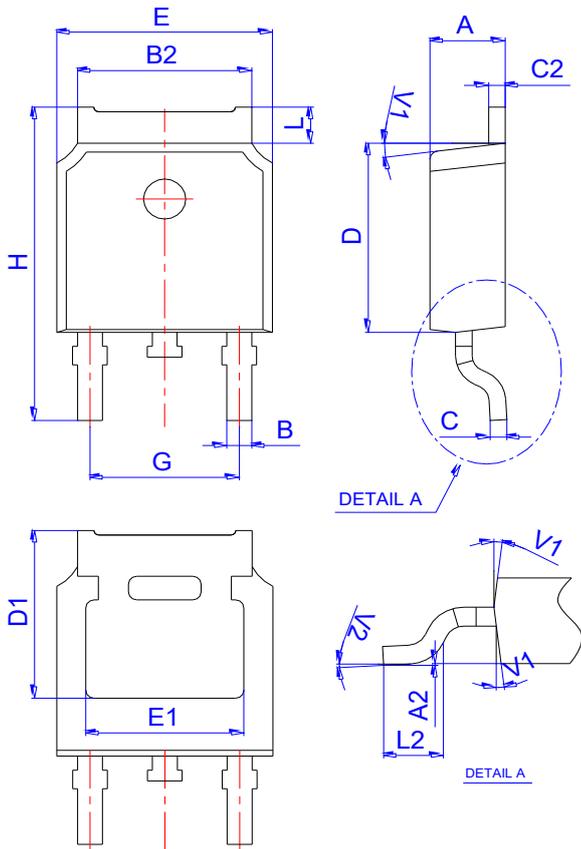
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Package Outline

TO-252

Dimensions in mm



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	2.10		2.50	0.083		0.098
A2	0		0.10	0		0.004
B	0.66		0.86	0.026		0.034
B2	5.18		5.48	0.202		0.216
C	0.40		0.60	0.016		0.024
C2	0.44		0.58	0.017		0.023
D	5.90		6.30	0.232		0.248
D1	5.30REF			0.209REF		
E	6.40		6.80	0.252		0.268
E1	4.63			0.182		
G	4.47		4.67	0.176		0.184
H	9.50		10.70	0.374		0.421
L	1.09		1.21	0.043		0.048
L2	1.35		1.65	0.053		0.065
V1		7°			7°	
V2	0°		6°	0°		6°